

2025 IEEE Electrical Design of Advanced Packaging and Systems (EDAPS 2025)

**Hokkaido, Japan
15-17 December 2025**

IEEE Catalog Number:
ISBN:

CFP25EDP-POD
979-8-3315-9660-6



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IEEE Catalog Number:	CFP25EDP-POD
ISBN (Print-On-Demand):	979-8-3315-9660-6
ISBN (Online):	979-8-3315-9659-0
ISSN:	2151-1225

Additional Copies of This Publication Are Available From:

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